

**SURFACE MOUNT
GLASS PASSIVATED RECTIFIER**

**REVERSE VOLTAGE – 1000 Volts
FORWARD CURRENT –2.0 Ampere**

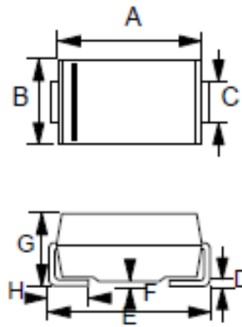
FEATURES

- For surface mounted applications.
- Low reverse leakage current
- Low forward voltage drop
- High current capability
- Qualification is according to AEC-Q101 Rev_C

MECHANICAL DATA

- Case: Molded plastic
- Case Material: “Green” molding compound, UL flammability classification 94V-0, (No Br. Sb. Cl.) “Halogen-free”
- Terminals: Lead Free Plating (Matte Tin Finish.)
- Component in accordance to RoHs 2002/95/EC
- Marking code: S2MAD
- Weight: 0.002 ounce, 0.064 grams (Approximate)

SMA



SMA		
DIM.	MIN.	MAX.
A	4.06	4.57
B	2.29	2.92
C	1.27	1.63
D	0.15	0.31
E	4.83	5.59
F	0.05	0.20
G	2.01	2.40
H	0.76	1.52
All dimension in millimeter		

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

ABSOLUTE RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Maximum repetitive peak reverse voltage	V _{RRM}	1000	V
Average rectified output current T _c = 80°C	I _(AV)	2.0	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load.	I _{FSM}	50	A
I ² t rating for fusing (t = 8.3ms)	I ² t	20.75	A ² S
Operating junction temperature range	T _J	-55 to +150	°C
Storage temperature range	T _{STG}	-55 to +150	°C

STATIC ELECTRICAL CHARACTERISTICS

PARAMETER	TEST CONDITIONS	SYMBOL	TYP.	MAX	UNIT
Forward voltage	I _F = 2A T _J = 25°C	V _F	--	1.1	V
Leakage current	V _R = 1000V T _J = 25°C T _J = 125°C	I _R	--	5.0 125	uA
Typical junction capacitance (Note 1)		C _J		15	pF

THERMAL CHARACTERISTICS

THERMAL CHARACTERISTIC	SYMBOL	TYP.	UNIT
Typical thermal resistance (Note 2)	R _{thJc} R _{thJL} R _{thJA}	40 15 45	°C/W

DYNAMIC ELECTRICAL CHARACTERISTICS

PARAMETER	TEST CONDITION	SYMBOL	MIN.	MAX	UNIT
Reverse recovery time	I _F = 0.5A, I _{rrf} = 0.25A, I _R = 1.0A T _J = 25°C	T _{RR}	500	1000	nS

Note :

- (1) Measured at 1.0MHz and applied voltage of 4.0VDC.
- (2) Thermal resistance test performed in accordance with JESD-51. Unit mounted on glass-epoxy substrate with 1oz/ft² 5 mm x 7 mm copper pad per pin.

REV.-0 Jul.-2019, KSDC09

RATING AND CHARACTERISTIC CURVES S2MAD

FIG.1- FORWARD CURRENT DERATING CURVE

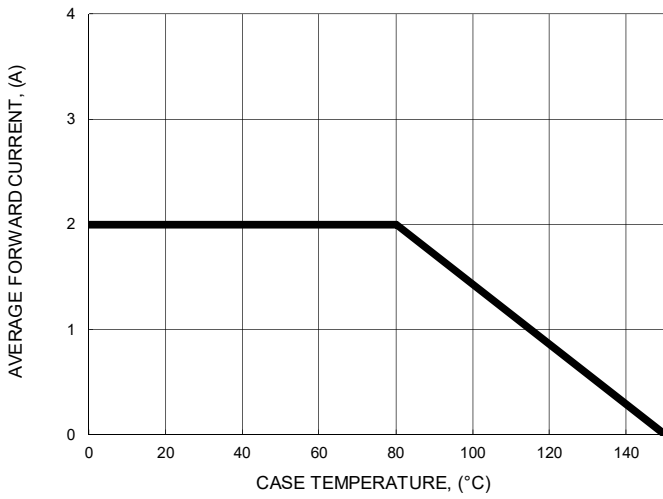


FIG.2- MAXIMUM NON-REPETITIVE SURGE CURRENT

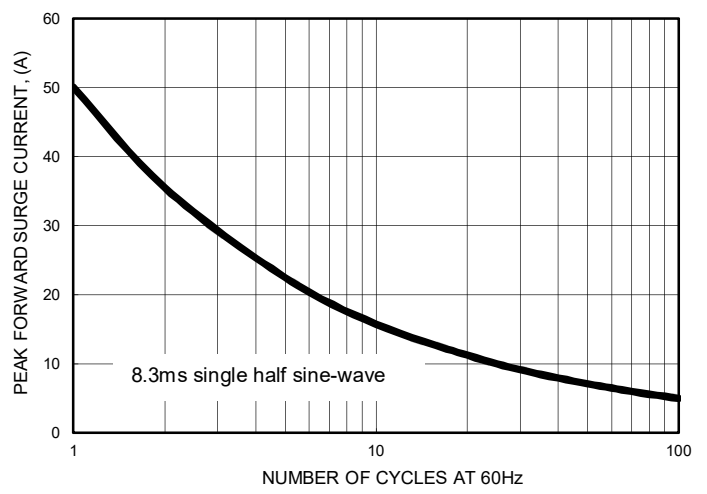


FIG.3- TYPICAL FORWARD CHARACTERISTICS

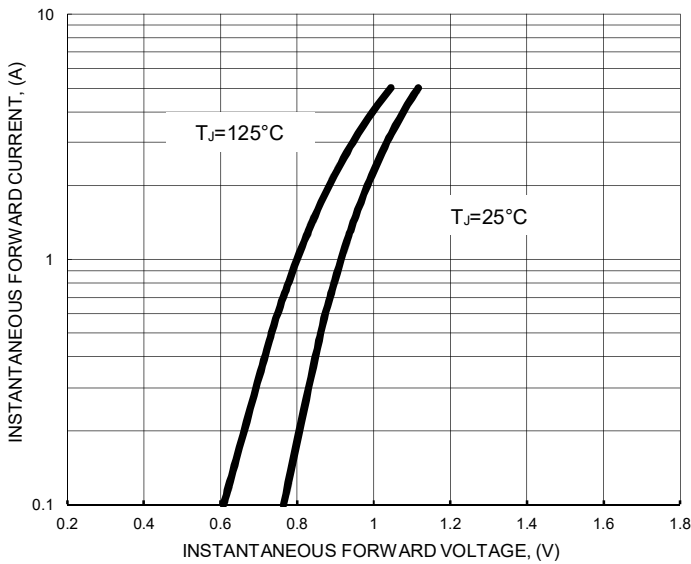


FIG.4- TYPICAL JUNCTION CAPACITANCE

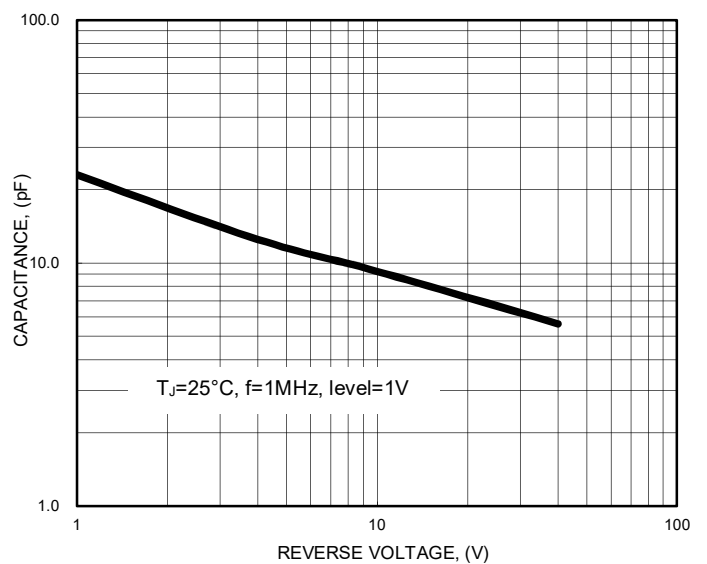
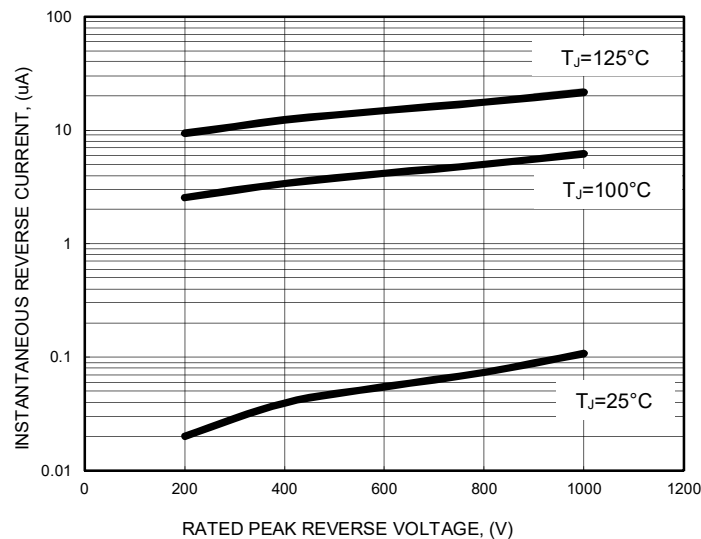


FIG.5- TYPICAL REVERSE CHARACTERISTICS

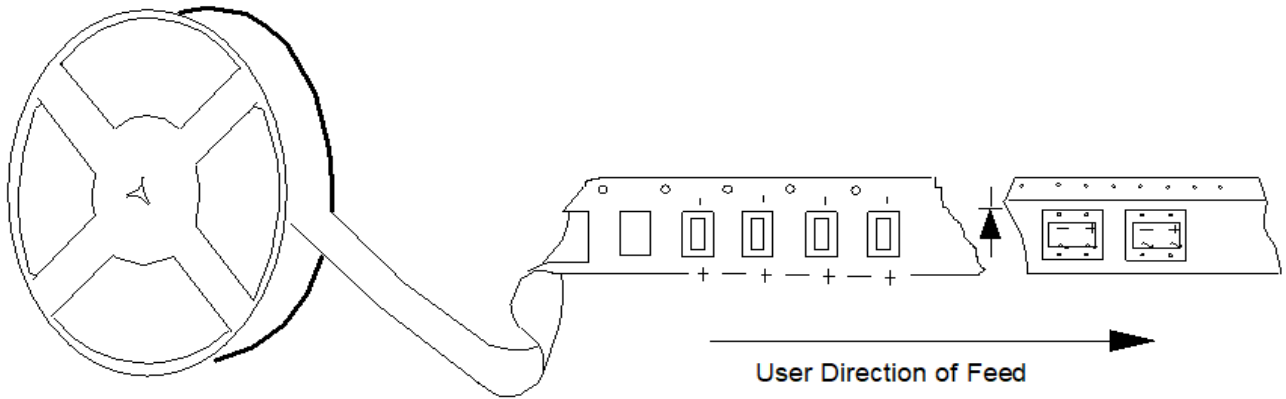


PACKAGING AND CARRIER DIMENSIONS INFORMATION
S2MAD



Packaging Information

Polar Units

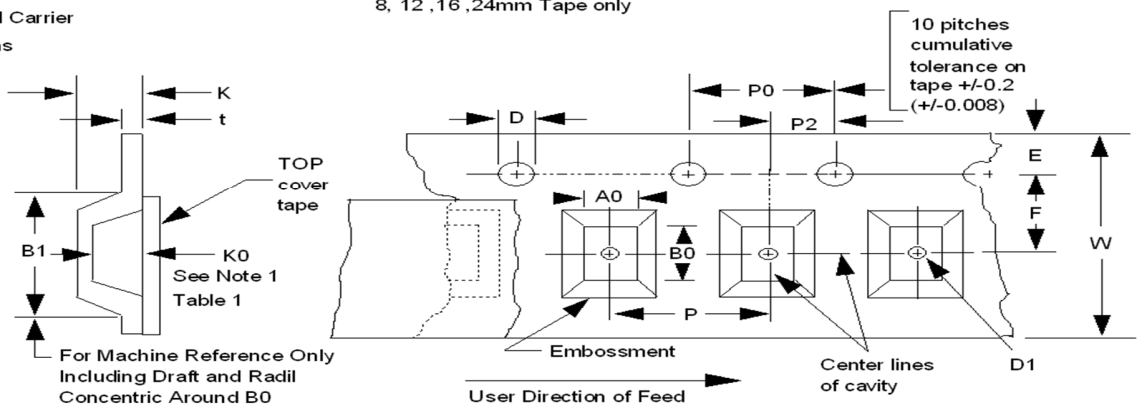


DEVICE	Q'TY/REEL (PCS)	REEL DIA. (mm)	BOX SIZE (mm)	Q'TY/BOX (PCS)	CARTON SIZE (mm)	Q'TY/CARTON (PCS)
S2MAD	5K	330	340X340X21	5K	350X350X340	60K

Embossed Carrier Dimensions Information

Packed per EIA/JEDEC standard RS-481
 8, 12, 16, 24mm Tape only

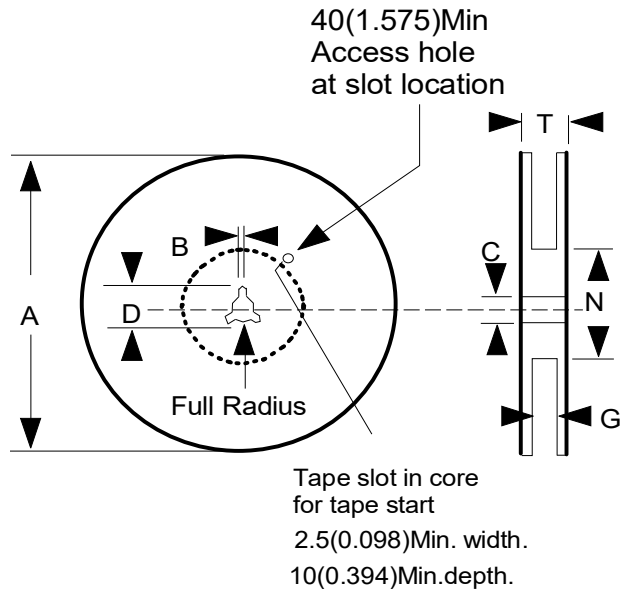
Embossed Carrier Dimensions



TAPE SIZE	D	E	PO	t(MAX)	W	P	UNIT
12mm	1.55+0.10/-0.0	1.75±0.10	4.0+0.1	0.4	12.0±0.30	4.0±0.1	mm
	B1(MAX)	D1(MIN)	F	K(MAX)	P2	A0B0K0	
	8.2	1.5	5.5±0.1	4.5	2.0±0.05	SEE NOTE 1	

Note 1: A0B0K0 are determined by component size. The clearance between the component and the cavity must be within 0.05 min. to 0.50 max. for 8 mm tape. 0.05 min. to 0.65 max. for 12mm tape. 0.15 min. to 0.90 max. for 16mm tape and 0.05 min. to 1.00 max. for 24 mm tape and larger.

PACKAGING AND CARRIER DIMENSIONS INFORMATION
S2MAD



TAPE SIZE	A MAX	B MIN	C	D MIN	N	G	T MAX	UNIT
12mm	178/330	1.5	13.0+/-0.5	20.2	75	12.4+2.0/-0.0	18.4	mm

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